

# MA3U749

## Silicon epitaxial planar type (cathode common)

For switching mode power supply

### ■ Features

- Low forward voltage  $V_F$
- Cathode-common dual type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	$V_{RRM}$	40	V
Forward current (Average)	$I_{F(AV)}$	5	A
Non-repetitive peak forward surge current *	$I_{FSM}$	40	A
Junction temperature	$T_j$	-40 to +125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +125	$^\circ\text{C}$

Note) \*: Half sine wave; 10 ms/cycle

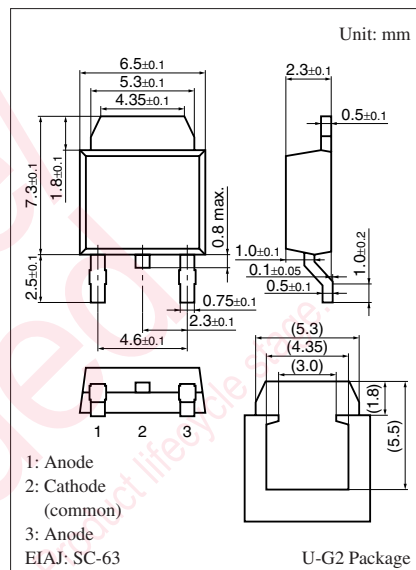
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

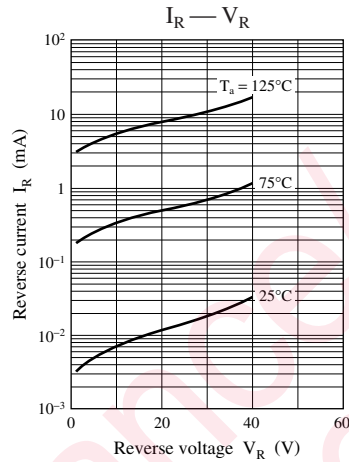
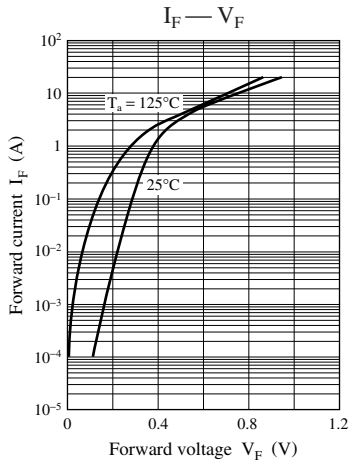
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 2.5\text{ A}$ , $T_C = 25^\circ\text{C}$			0.55	V
Reverse current	$I_R$	$V_R = 40\text{ V}$ , $T_C = 25^\circ\text{C}$			1.0	mA
Thermal resistance (j-c) *	$R_{th(j-c)}$				12.5	$^\circ\text{C/W}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. \*:  $T_C = 25^\circ\text{C}$





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